

Appl. No. 10/538,136  
Reply to Office Action of November 29, 2007

Amendments to the Specification:

Please replace the second paragraph on page 4 with the following amended paragraph:

The present invention is based on facts which have been found that a multilayer ceramic electronic part which is excellent in bonding-property between an internal electrode(s) and an external electrode(s) and suitable for its mounting on a substrate and for the plating-treatment can be obtained by using a metal powder having a melting point of 300°C or less together in addition to [[a]] conventional conductive particles having a high melting point for a thermosetting conductive paste which forms an external electrode(s).

Please replace the last paragraph on page 28 with the following amended paragraph:

An external electrode(s) of a multilayer ceramic electronic part of the present invention is formed from a thermosetting conductive paste which can be cured at a low temperature. Thus the multilayer ceramic electronic part does not have any defect due to high-temperature firing, which was found in a multilayer ceramic electronic part from a conventional fired-type conductive paste,

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and further can be obtained without using a nitrogen atmosphere at the time of firing. Besides, the multilayer ceramic electronic part of the present invention causes no deterioration of electric properties, differing from the one obtained from a conventional thermosetting conductive paste. Accordingly, a multilayer ceramic electronic part which is excellent in electric properties and suitable for the mounting on a substrate and for ~~the plating-~~ treatment is has been able to be obtained.